

# MXP6006CT Preliminary Datasheet

# 60V N-Channel MOSFET

# **Applications:**

- Power Supply
- DC-DC Converters

V <sub>DSS</sub>	R <sub>DS(ON)</sub> (Max)	ا <sub>D</sub> <sup>a</sup>	
60 V	6.0 mΩ	116 A	

#### Features:

- LeadFree
- Low R<sub>DS(ON)</sub> to Minimize Conductive Loss
- Low Gate Change for Fast Switching Application
- Optimized B<sub>VDSS</sub> Capability

### **Ordering Information**

Part Number	Package	Brand
MXP6006CT	TO220	MXP

#### **Absolute Maximum Ratings**

 $T_c=25^{\circ}C$  unless otherwise specified

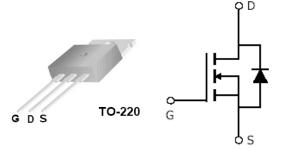
Symbol	Parameter	Value	Units
V <sub>DS</sub>	Drain-to-Source Voltage	60	V
I <sub>D</sub> <sup>a</sup>	Continuous Drain Current $(T_c=25^{\circ}C)$	116	٨
I <sub>DM</sub>	Pulsed Drain Current @V <sub>G</sub> =10V	463	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (L=11.9mH)	960	mJ
$T_{\rm J}$ and $T_{\rm STG}$	Operating Junction and Storage Temperature Range	-55 to 175	°C

a. Calculated continuous current based upon maximum allowable junction temperature, +175°C. Package limitation current is 80A.

#### **OFF Characteristics**

 $T_J$ =25°C unless otherwise specified

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	60			V	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA
I <sub>DSS</sub>	Drain-to-Source Leakage Current			1	μA	$V_{DS}$ =48V, $V_{GS}$ =0V
				100		$V_{DS}$ =48V, $V_{GS}$ =0V T <sub>J</sub> =125 $^{\circ}$ C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	<b>n</b> A	V <sub>GS</sub> =+20V
	Gate-to-Source Reverse Leakage			100	– nA	V <sub>GS</sub> = -20V



# **ON** Characteristics

 $T_J {=} 25^\circ\! \mathrm{C}$  unless otherwise specified

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
R <sub>DS(ON)</sub>	Static Drain-to-Source On-Resistance			6	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> =24A
V <sub>GS(TH)</sub>	Gate Threshold Voltage	2		4	V	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$

**Dynamic Characteristics** Essentially independent of operating temperature

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
C <sub>iss</sub>	Input Capacitance		4073			
C <sub>oss</sub>	Output Capacitance		522		pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz
C <sub>rss</sub>	Reverse Transfer Capacitance		181			
Qg	Total Gate Charge		61		nC	V <sub>DD</sub> =30V, I <sub>D</sub> =58A, V <sub>G</sub> =10V
Q <sub>gs</sub>	Gate-to-Source Charge		26			
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge		18			
t <sub>d(on)</sub>	Turn-on Delay Time		17			$V_{DD}$ =30V, I <sub>D</sub> =58A, V <sub>G</sub> =10V, R <sub>G</sub> =2.5Ω
t <sub>r</sub>	Rise Time		52		ns	
t <sub>d(off)</sub>	Turn-off Delay Time		38			
t <sub>f</sub>	Fall Time		14			

# **Source-Drain Diode Characteristics**

Tc=25 $^{\circ}$ C unless otherwise specified

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
V <sub>SD</sub>	Diode Forward Voltage			1.2	V	I <sub>S</sub> =24A, V <sub>GS</sub> =0V

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